Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)

Contact Info: ti.com/support

Form/Declaration Type: Distribute - RoHS and IEC 62474 DB

Created on: **06/08/2022**

Details for "TLV2186IDSGT"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLV2186IDSGT	NIPDAU	Level-1-260C-UNLIM	TI Semiconductor	DSG 8	2x2x0.75	11.8

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS		REACH	Green	IEC 62474 DB	
	Yes	Yes	Yes	Yes	

Component Information

				Homoge	neous Material Level	Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire				,			
Copper and Its Alloys	Copper	7440-50-8	0.02129	97.535276	975353	0.180263	1803
Not Categorized	Proprietary Materials		0.000002	0.009163	92	0.000017	0
Precious Metals	Gold	7440-57-5	0.000011	0.050394	504	0.000093	1
Precious Metals	Palladium	7440-05-3	0.000524	2.400586	24006	0.004437	44
Precious Metals	Silver	7440-22-4	0.000001	0.004581	46	0.000008	0
Sub-Total			0.021828	100	1000000	0.184818	1848
Die Attach Adhesive	•	•					
Precious Metals	Silver	7440-22-4	0.20944	80	800000	1.773329	17733
Thermoplastics	Ероху	85954-11-6	0.05236	20	200000	0.443332	4433
Sub-Total			0.2618	100	1000000	2.216662	22167
Lead Frame	<u> </u>	<u> </u>	•				
Copper and Its Alloys	Copper	7440-50-8	6.8264	97.52	975200	57.799156	577992
Copper and Its Alloys	Iron	7439-89-6	0.161	2.3	23000	1.363188	13632
Copper and Its Alloys	Phosphorus	7723-14-0	0.0021	0.03	300	0.017781	178
Zinc and Its Alloys	Zinc	7440-66-6	0.0105	0.15	1500	0.088904	889
Sub-Total			7	100	1000000	59.269028	592690
Lead Frame Plating	<u> </u>	•	•				
Nickel and Its Alloys	Nickel	7440-02-0	0.19024	95.12	951200	1.610763	16108
Precious Metals	Gold	7440-57-5	0.00156	0.78	7800	0.013209	132
Precious Metals	Palladium	7440-05-3	0.0082	4.1	41000	0.069429	694
Sub-Total			0.2	100	1000000	1.693401	16934
Mold Compound	•	•					
Other Inorganic Materials	Fused Silica	60676-86-0	3.297958	88.000013	880000	27.923824	279238
Other Organic Materials	Chlorine	7782-50-5	0.000037	0.000987	10	0.000313	3
Other Plastics and Rubber	Carbon Black	1333-86-4	0.011243	0.299999	3000	0.095195	952
Thermoplastics	Ероху	85954-11-6	0.438441	11.699001	116990	3.712282	37123
Sub-Total			3.747679	100	1000000	31.731613	317316
Semiconductor Device	<u> </u>	•	•		•		-
Ceramics / Glass	Doped Silicon	7440-21-3	0.579246	100	1000000	4.904478	49045
Sub-Total			0.579246	100	1000000	4.904478	49045
Total			11.810553			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/08/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.